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	SOT1789-1	29 JAN 2016



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION H IS MEASURED .030 (0.762) AWAY FROM PACKAGE BODY.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER		
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX	
A	.905	– .915	22.99	– 23.24	aaa	– .007	–	–	0.178	–
B	.535	– .545	13.59	– 13.84	bbb	– .010	–	–	0.254	–
C	.147	– .200	3.73	– 5.08	ccc	– .015	–	–	0.381	–
D	.495	– .505	12.57	– 12.83	–	–	–	–	–	–
E	.035	– .045	0.89	– 1.14	–	–	–	–	–	–
F	.003	– .006	0.08	– 0.15	–	–	–	–	–	–
H	.057	– .067	1.45	– 1.70	–	–	–	–	–	–
K	.170	– .210	4.32	– 5.33	–	–	–	–	–	–
M	.872	– .888	22.15	– 22.56	–	–	–	–	–	–
N	.871	– .889	22.12	– 22.58	–	–	–	–	–	–
R	.515	– .525	13.08	– 13.34	–	–	–	–	–	–
S	.515	– .525	13.08	– 13.34	–	–	–	–	–	–

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